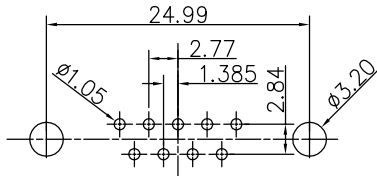
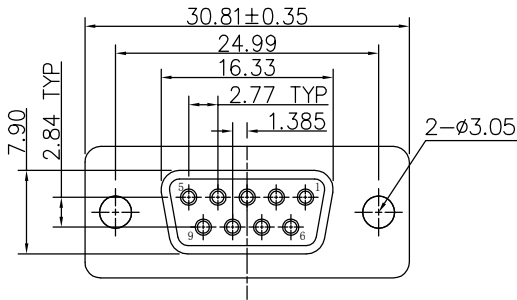
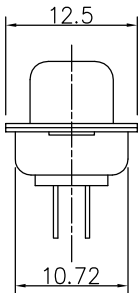
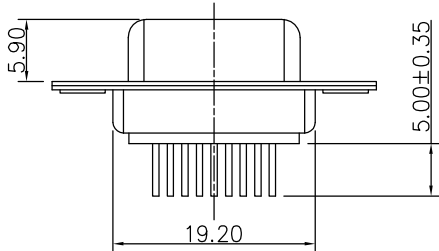


The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements

RoHS



PCB layout



- NOTE
- 1.MATERIAL:
- 1.1 INSULATOR: PBT+30% GLASS FIBER UL94V-0
COLOR:BLACK
 - 1.2 TERMINAL: COPPER ALLOY BRASS T=0.20±0.02mm
GOLD FLASH ON CONTACT AREA AND TIN 80U" ON SOLDER TAIL; NICKEL:30U" ON THE BASE
 - 1.3 SHELL: FRONT SHELL:SPCC-SD T=0.35±0.02mm
PLATING:Cu50u"/Ni50u" ;
REAR SHELL:SPCC-SD T=0.35±0.02mm
PLATING:Cu50u"/Tin80u"
 - 1.4 BOARD LOCK: COPPER ALLOY, PLATING: Cu50u"/Ni40u"
 - 1.5 SCREW: STEEL, PLATING: Cu50u"/Ni40u"
 - 1.6 SALT SPRAY: PLATING GOLD, 24H; OTHER PART: 12H .
- 2.ELECTRICAL:
- 2.1 INSULATOR RESISTANCE: 1000MEGOHMS MIN AT 500V DC.
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC R.M.S
 - 2.3 VOLTAGE TATING: 40V AC (RMS) CONTINUOUS MAX.
 - 2.4 CURRENT RATING: 3A.
 - 2.5 CONTGACT RESISTANCE: 30 MILLIOHMS MAX.
- 3.MECHANICAL
- 3.1 INSERTION/EXTRACTION FORCE PER CONTACT: 3.0Kgf Max
0.3Kgf Min.
- 4.ENVIRONMENTAL
- TEMPERATURE RANGE:-55°C TO + 105°C.

Specification Type			
A	B	C	D

ORDER INFORMATION

P/N: WLDBF0-091XXX026

Number of Contact

Contact Type
1: DIP

Plating Contact
1: Gold Flash
3: Au: 3U"
6: Au: 30U"

SCREW

Housing color
A: Black
S: Nature

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO: WLDBF0—091XXX026	DWG.NO: ENDE05	
A0	NEW RELEASE	21.01.13		LINEAR	ANGLES	APPROVED	Wang_jr	21.01.13			
A1	ADD MATERIAL THICK AND PLATING 	23. 04. 27		0.0±0.35	X°REF±6°	DESIGNER	Ou_jian	21.01.13	TITLE: DP 09F DIP		
				UNIT:mm	0.00±0.25	X°±3°	DRAWN	Hou—lanxuan			21.01.13
				SIZE: A4	0.000±0.10	X°X° ±2°					

WanLian Technology Co., Ltd

REV: A0

SHEET: 1/1